L Number	Hits	Search Text	DB	Time stamp
1	1773		USPAT	2004/06/11 15:40
2	29	"bonded structure" and (((circuit near	USPAT	2004/06/11 16:36
		board) or substrate) and (borosilicate or		
		rbm)).detd.		
4	27		USPAT	2004/06/11 16:57
		board) or substrate) and (borosilicate or		
		rbm)).detd.) and (oxygen or oxide or		
_		oxidiz\$)		0004/06/11 15 45
5	26	, , ,	USPAT	2004/06/11 15:45
		board) or substrate) and (borosilicate or		
		rbm)).detd.) and (oxygen or oxide or oxidiz\$)) and (heat or thermal or infrared		
		or ir)		
6	24	((("bonded structure" and (((circuit near	USPAT	2004/06/11 15:55
ľ		board) or substrate) and (borosilicate or	*****	2001, 00, 11 10.00
		rbm)).detd.) and (oxygen or oxide or		-
		oxidiz\$)) and (heat or thermal or infrared		
		or ir)) and (sens\$ or detect\$ or		
		measur\$).detd.		
7	27	(("bonded structure" and (((circuit near	USPAT	2004/06/11 15:45
		board) or substrate) and (borosilicate or		
		rbm)).detd.) and (oxygen or oxide or		
		oxidiz\$)) and (heat or thermal or infrared		
8	25	or ir or temperature) ((("bonded structure" and (((circuit near	USPAT	2004/06/11 15:54
0	23	board) or substrate) and (borosilicate or	OSFAI	2004/00/11 15.54
		rbm)).detd.) and (oxygen or oxide or		
		oxidiz\$)) and (heat or thermal or infrared		
		or ir or temperature)) and (sens\$ or		
		detect\$ or measur\$).detd.		
9	5	,,, =================================	USPAT	2004/06/11 16:24
		board) or substrate) and (borosilicate or		
		rbm)).detd.) and (oxygen or oxide or		
		oxidiz\$)) and (heat or thermal or infrared		
		or ir or temperature)) and ((sens\$ or detect\$ or measur\$) near2 (heat or thermal		
		or temperature)).detd.		
10	l 0		USPAT }	2004/06/11 16:33
	Ī	((facility or factory) with (alert\$ or		
		alarm\$ or warn\$) with (temperature or heat		
		or gas))).detd.		
11	301	,,	USPAT	2004/06/11 16:35
		wafer\$1 or semicondcutor\$1)) and		
		((substrate\$1 or wafer\$1 or		
		semicondcutor\$1) with ((temperature or		
		heat or gas or environment\$) near2 (sens\$ or detect\$ or measur))).detd.		
12	50		USPAT	2004/06/11 16:35
**		wafer\$1 or semicondcutor\$1)) and	JOSEKI	2004/00/11 10.33
		((substrate\$1 or wafer\$1 or		
		semicondcutor\$1) with ((temperature or		
		heat or gas or environment\$) near2 (sens\$		
		or detect\$ or measur)))).detd.) and		
		(facility or factory or		
1		manufacturer).detd.		
13	<sup>1</sup>	((((manufactur\$ near3 (substrate\$1 or	USPAT	2004/06/11 16:36
1		wafer\$1 or semicondcutor\$1)) and		
		((substrate\$1 or wafer\$1 or		
		semicondcutor\$1) with ((temperature or heat or gas or environment\$) near2 (sens\$		
		or detect\$ or measur)))).detd.) and		
		(facility or factory or		
		manufacturer).detd.) and (((circuit near		
		board) or substrate) and (borosilicate or		
L	<u> </u>	rbm)).detd.		

14	1	(((((manufactur\$ near3 (substrate\$1 or	USPAT	2004/06/11 16:57
	i	wafer\$1 or semicondcutor\$1)) and		
	1	((substrate\$1 or wafer\$1 or		
		semicondcutor\$1) with ((temperature or		
		heat or gas or environment\$) near2 (sens\$		
		or detect\$ or measur)))).detd.) and		
		(facility or factory or		
		manufacturer).detd.) and (((circuit near		
		board) or substrate) and (borosilicate or		
		rbm)).detd.) and (oxygen or oxide or		
1		oxidiz\$)		